

APPLICABLE STANDARD					
Rating	Operating Temperature Range	-40 °C to 140 °C <sup>(1)</sup>	Storage Temperature Range	-10 °C to 60 °C <sup>(2)</sup>	
	Voltage	125 V AC <sup>(3)</sup>	Storage Humidity Range	Relative humidity 60% max (Not dewed)	
	Current	0.5 A	Operating Humidity Range	Relative humidity 85% max (Not dewed)	
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	
CONSTRUCTION				QT	AT
General Examination		Examined visually and with a measuring instrument.		x	x
Marking		Confirmed visually.		x	x
ELECTRICAL CHARACTERISTICS					
Contact Resistance	Measured at 100 mA MAX.(DC or 1000Hz)		65mΩ MAX.	x	—
Insulation Resistance	Measured at 250 V DC.		1000 MΩ MIN.	x	—
Voltage Proof	375 V AC applied for 1 min.		No flashover or breakdown.	x	—
MECHANICAL CHARACTERISTICS					
Mating and Unmating Forces	Measured with an applicable connector.		Mating Force: 60 N MAX. Unmating Force: 6.6 N MIN.	x	—
Mechanical Operation	Mated and unmated 10 times.		①Contact Resistance : 75mΩ MAX. ②No damage, cracks or looseness of parts.	x	—
Vibration	Frequency 50~100 → 100~150 → 150~300Hz Acceleration 98 → 98~294 → 294 m/s <sup>2</sup> 1 cycle 3 min 3 h for 3 axial directions <sup>(4)</sup>		①No electrical discontinuity of more than 1 μs. ②No damage, cracks or looseness of parts.	x	—
Shock	Acceleration 980 m/s <sup>2</sup> , duration of pulse 6 ms at 3 times for 3 axial directions.			x	—
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)	Exposed at 60±2 °C, 90 ~ 95 %, 1000 h.		①Contact Resistance : 75mΩ MAX. ②Insulation Resistance : 1000 MΩ MIN. △2	x	—
Rapid Change of Temperature	Temperature -40 → +140 °C Time 30 → 30 min. under 1000 cycles. (Relocation time to chamber : within 2~3 MIN)		③No damage, cracks or looseness of parts.	x	—
Cold	Exposed at -40°C, 1000 h		①Contact Resistance : 75mΩ MAX.	x	—
Dry Heat	Exposed at 140°C, 1000 h		②No damage, cracks or looseness of parts.	x	—
Sulfur Dioxide	Exposed at 40±2°C, 80±5%RH, 25±5 PPM for 96 h.		Contact Resistance : 75mΩ MAX.	x	—
Resistance to Soldering Heat	1)Reflow soldering : Peak TMP : 260°C MAX Reflow TMP: 220°C MIN for 60sec. △1		No deformation of case of excessive looseness of the terminal.	x	—
Solderability	Soldered at solder temperature 240±3°C for immersion duration, 3 sec.		A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	x	—
COUNT	DESCRIPTION OF REVISIONS		DESIGNED	CHECKED	DATE
△2 1	DIS-F-00016361		TK. ABE	HH. SHINDO	20221215
<b>Notes</b> <sup>(1)</sup> Include temperature rise caused by current-carrying. <sup>(2)</sup> "STORAGE" means a long-term storage state for the unused product before assembly to PCB. <sup>(3)</sup> The creepage distance conforms to IEC 60664-1. Voltage effective value: 32V AC, Pollution Degree: 2 <sup>(4)</sup> Amplitude between connector mounting part and PCB is 0.05mm MAX.			APPROVED	HH. SHINDO	20190719
			CHECKED	KN. SHIBUYA	20190718
			DESIGNED	TK. ABE	20190718
			DRAWN	TK. ABE	20190718
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-376652-00-00
<b>HRS</b>	SPECIFICATION SHEET		PART NO.	FX26-60S-1SV20	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL0576-1306-0-00	△2 1/1